

**Amendments to the Claims:** This listing of claims will replace all prior versions, and listings, of claims in the application

Listing of Claims:

1.-36. (Canceled)

37. (Original) A clad board for forming circuitry, being manufactured through:

sticking a releasing film to a pre-preg sheet;

forming a hole in the pre-preg sheet with the releasing film, the hole being one of a non-through-hole and a through-hole;

filling the hole with conductive paste;

peeling off the releasing film; and

heating and pressing a metal foil onto the pre-preg sheet,

said clad board comprising:

a fiber sheet included in the pre-preg sheet;

resin material impregnated into the fiber sheet, the resin material including at least one of thermoplastic resin and thermosetting resin having semi-cured portion; and

a resin layer formed smoothly on the fiber sheet, the resin layer being made of material identical to the resin material.

38.-39. (Canceled)

40. (Original) A clad board for forming circuitry, being manufactured through:

sticking a releasing film to a pre-preg sheet;

forming a hole in the pre-preg sheet with the releasing film, the hole being one of a non-through-hole and a through-hole;

filling the hole with conductive paste;

peeling off the releasing film; and

heating and pressing a metal foil onto the pre-preg sheet,

said board comprising:

a fiber sheet included in the pre-preg sheet, having a density ranging from 700kg/m<sup>3</sup> to 1000kg/m<sup>3</sup>; and

resin material impregnated into the fiber sheet, the resin material including at least one of thermoplastic resin and thermosetting resin having semi-cured portion.

41. (Original) A clad board for forming circuitry, being manufactured through:

sticking a releasing film to a pre-preg sheet;

forming a hole in the pre-preg sheet with the releasing film, the hole being one of a non-through-hole and a through-hole;

filling the hole with conductive paste;

peeling off the releasing film; and

heating and pressing a metal foil onto the pre-preg sheet,

said board comprising:

a fiber sheet included in the pre-preg sheet;

a first layer included in the fiber sheet and disposed at a surface of the fiber sheet;

a second layer included in the fiber sheet, the second layer having a density lower than a density of the first layer; and

resin material impregnated into the fiber sheet, the resin material including at least one of thermoplastic resin and thermosetting resin having semi-cured portion.

42.-43. (Canceled)

44. (Original) A clad board for forming circuitry, being manufactured through:

sticking a releasing film to a pre-preg sheet;

forming a hole in the pre-preg sheet with the releasing film, the hole being one of a non-through-hole and a through-hole;

filling the hole with conductive paste;

peeling off the releasing film; and

heating and pressing a metal foil onto the pre-preg sheet,

said board comprising:

a fiber sheet included in the pre-preg sheet;

a first layer included in said fiber sheet;

a second layer included in said fiber sheet, the second layer having a density different from a density of the first layer; and

resin material impregnated into the fiber sheet, the resin material including at least one of thermoplastic resin and thermosetting resin having semi-cured portion.

45.-46. (Canceled)

47. (Original) A clad board for forming circuitry, being manufactured through:

sticking a releasing film to a pre-preg sheet;

forming a hole in the pre-preg sheet with the releasing film, the hole being one of a non-through-hole and a through-hole;

filling the hole with conductive paste;

peeling off the releasing film; and

heating and pressing a metal foil onto the pre-preg sheet,

said board comprising:

a fiber sheet included in the pre-preg sheet;

first and second layers included in the fiber sheet, being disposed on respective surfaces of the fiber sheet;

a third layer included in the fiber sheet, being located between the first and second layers, the third layer having a density lower than respective densities of the first and second layers; and

resin material impregnated into the fiber sheet, the resin material including at least one of thermoplastic resin and thermosetting resin having semi-cured portion.

48.-52. (Canceled)

53. (Original) A clad board for forming circuitry, being manufactured through:

sticking a releasing film to a pre-preg sheet;

forming a hole in the pre-preg sheet with the releasing film, the hole being one of a non-through-hole and a through-hole;

filling the hole with conductive paste;

peeling off the releasing film; and

heating and pressing a metal foil onto the pre-preg sheet,

said clad board comprising:

a conductive particle included in the conductive paste, the conductive particle has a longest diameter greater than a size of a gap, in a thickness direction, produced at an interface between the releasing film and the pre-preg sheet in one of the sticking of the releasing film and the forming of the hole.

54.-58. (Canceled)

59. (Original) A clad board for forming circuitry, being manufactured through:

sticking a releasing film to a pre-preg sheet;

forming a hole in the pre-preg sheet including the releasing film, the hole being one of a non-through-hole and a through-hole;

filling the hole with conductive paste;

peeling off the releasing film; and

heating and pressing a metal foil onto the pre-preg sheet,

said clad board comprising:

a conductive particle included in the conductive paste, being shaped in non-spherical.

60.-65. (Canceled)

66. (Original) A core board for a clad board for forming circuitry, comprising:

a fiber sheet;

resin material impregnated into the fiber sheet, the resin material including at least one of thermoplastic resin and thermosetting resin having semi-cured portion; and

a resin layer formed on the fiber sheet, being made of material identical to the resin material.

67.-68. (Canceled)

69. (Original) A core board for a clad board for forming circuitry, comprising:

a fiber sheet having a density ranging from  $700\text{kg/m}^3$  to  $1000\text{kg/m}^3$ ; and

resin material impregnated into the fiber sheet, the resin material including at least one of thermoplastic resin and thermosetting resin having semi-cured portion.

70. (Original) A core board for a clad board for forming circuitry, comprising:

a fiber sheet;

a first layer included in the fiber sheet and disposed at a surface of the fiber sheet;

a second layer included in the fiber sheet, having a density lower than a density of the first layer; and

resin material impregnated into the fiber sheet, the resin material including at least one of thermoplastic resin and thermosetting resin having semi-cured portion.

71.-72. (Canceled)

73. (Original) A core board for a clad board for forming circuitry, comprising:

a fiber sheet;

a first layer included in the fiber sheet;

a second layer included in the fiber sheet, having a density different from a density of the first layer; and

resin material impregnated into the fiber sheet, the resin material including at least one of thermoplastic resin and thermosetting resin having semi-cured portion.

74.-75. (Canceled)

76. (Original) A core board for a clad board for forming circuitry, comprising:

a fiber sheet;

first and second layers included in the fiber sheet, being disposed on respective outermost sides of the fiber sheet;

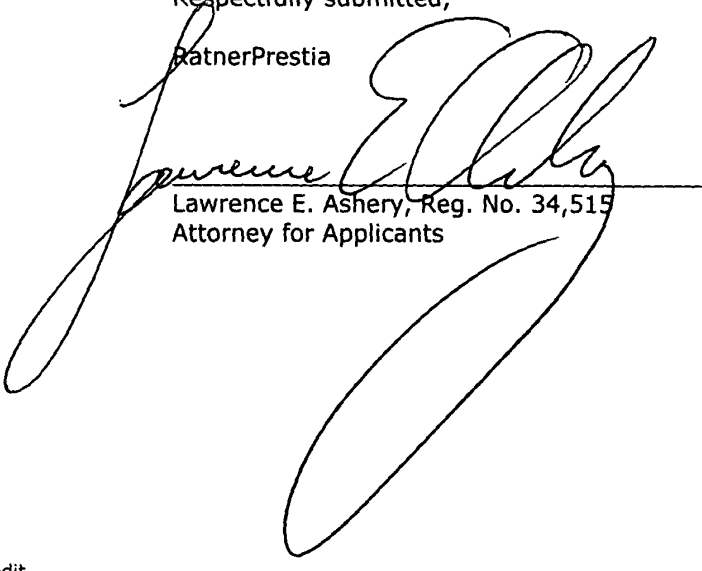
a third layer included in said fiber sheet, being located between the first and second layers, having a density lower than respective densities of the first and second layers; and

resin material impregnated into the fiber sheet, the resin material including at least one of thermoplastic resin and thermosetting resin having semi-cured portion.

77.-82. (Canceled)

Respectfully submitted,

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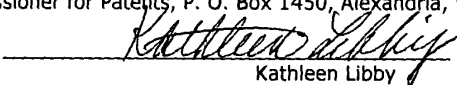
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